

# FDMS86104 Datasheet



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DiGi Electronics Part Number FDMS86104-DG

Manufacturer onsemi

Manufacturer Product Number FDMS86104

Description MOSFET N-CH 100V 7A/16A 8PQFN

Detailed Description N-Channel 100 V 7A (Ta), 16A (Tc) 2.5W (Ta), 73W (

Tc) Surface Mount 8-PQFN (5x6)



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# **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
FDMS86104	onsemi
Series:	Product Status:
PowerTrench®	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
100 V	7A (Ta), 16A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
6V, 10V	24m0hm @ 7A, 10V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
4V @ 250μA	16 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	923 pF @ 50 V
FET Feature:	Power Dissipation (Max):
	2.5W (Ta), 73W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
8-PQFN (5x6)	8-PowerTDFN
Base Product Number:	
EDMC06	

# **Environmental & Export classification**

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



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October 2014

# FDMS86104

# N-Channel Shielded Gate PowerTrench<sup>®</sup> MOSFET 100 V, 16 A, 24 m $\Omega$

#### **Features**

- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)}$  = 24 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 7 A
- Max  $r_{DS(on)}$  = 39 m $\Omega$  at  $V_{GS}$  = 6 V,  $I_D$  = 5.5 A
- Advanced Package and Silicon combination for low r<sub>DS(on)</sub> and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant



### **General Description**

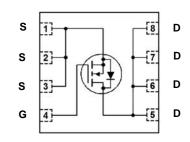
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

## **Application**

■ DC-DC Conversion







### MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
$V_{DS}$	Drain to Source Voltage			100	V
$V_{GS}$	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T <sub>C</sub> = 25 °C		16	
$I_D$	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	7	Α
	-Pulsed			30	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	96	mJ
D	Power Dissipation	T <sub>C</sub> = 25 °C		73	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.5	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a	50	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86104	FDMS86104	Power 56	13 "	12 mm	3000 units

## **Electrical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter	lest Conditions	MIIN	тур	IVIAX	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		66		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	2.9	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-10		mV/°C
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A		20	24	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 5.5 \text{ A}$		27	39	mΩ
, ,		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A, T <sub>J</sub> = 125 °C		33	40	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 7 A		18		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz	694	923	pF
Coss	Output Capacitance		178	237	рF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1/1/12	8	13	pF
$R_q$	Gate Resistance		0.5		Ω

#### **Switching Characteristics**

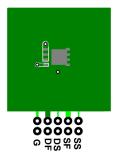
t <sub>d(on)</sub>	Turn-On Delay Time		8	16	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 50 \text{ V}, I_D = 7 \text{ A},$	3.5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	14.3	26	ns
t <sub>f</sub>	Fall Time		3.2	10	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	11.7	16	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}  V_{DD} = 50 \text{ V},$	6.7	9	
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = 7 A	3.2		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		3		nC

#### **Drain-Source Diode Characteristics**

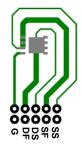
V	Veb 1500rce to Drain Dioge, Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$ (Note 2)	0.7	1.2	\/
V SD		$V_{GS} = 0 \text{ V}, I_S = 7 \text{ A}$ (Note 2)	0.8	1.3	v
t <sub>rr</sub>	Reverse Recovery Time	I - 7 A di/dt - 100 A/vo	44	70	ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 7 A, di/dt = 100 A/μs	41	65	nC

Notes

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

<sup>2.</sup> Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0%.

<sup>3.</sup> Starting T  $_{J}$  = 25 °C, L = 3 mH, I  $_{AS}$  = 8 A, V  $_{DD}$  = 100 V, V  $_{GS}$  = 10 V

## Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

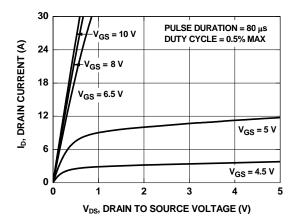


Figure 1. On-Region Characteristics

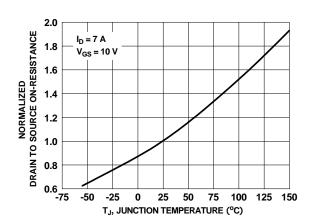


Figure 3. Normalized On-Resistance vs Junction Temperature

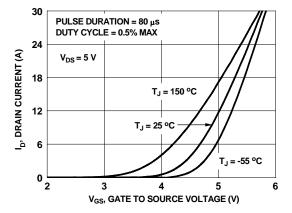


Figure 5. Transfer Characteristics

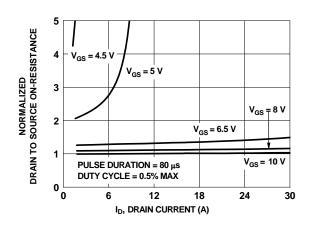


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

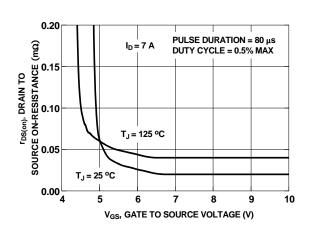


Figure 4. On-Resistance vs Gate to Source Voltage

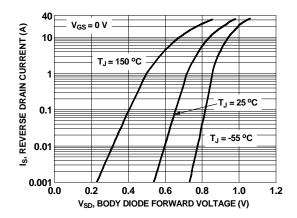


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

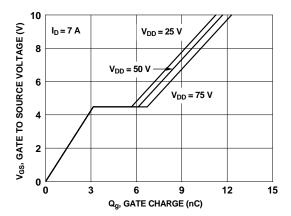


Figure 7. Gate Charge Characteristics

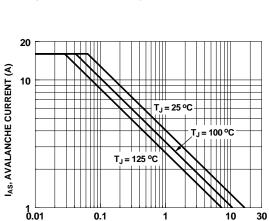


Figure 9. Unclamped Inductive **Switching Capability** 

t<sub>AV</sub>, TIME IN AVALANCHE (ms)

10

30

0.1

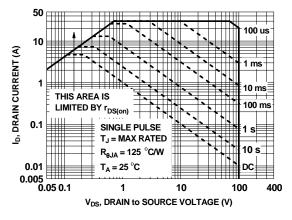


Figure 11. Forward Bias Safe **Operating Area** 

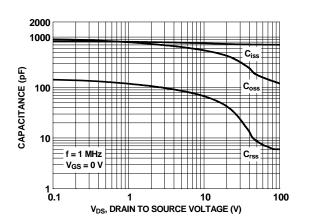


Figure 8. Capacitance vs Drain to Source Voltage

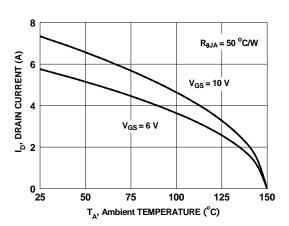


Figure 10. Maximum Continuous Drain **Current vs Ambient Temperature** 

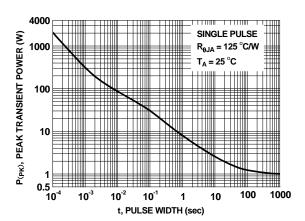


Figure 12. Single Pulse Maximum **Power Dissipation** 



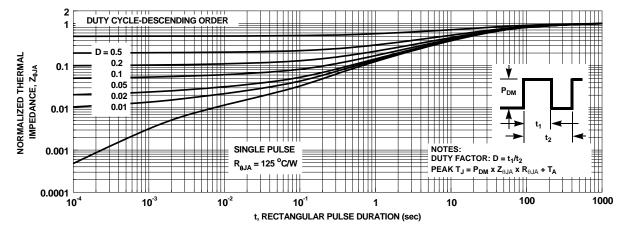


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

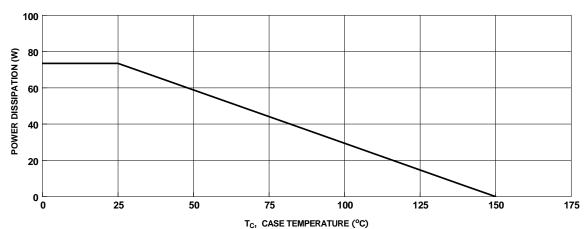


Figure 14. Power Vs Case Temperature

**BOTTOM VIEW** 

3.96

0.20<sup>+0.10</sup><sub>-0.15</sub>(8X)

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